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P30245.A01

Application No. 10/598,124

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Isao SAKAMOTO et al.

Group Art Unit : Not Yet Assigned

Appl. No. : 10/598,124 (U.S. National
Stage of PCT/JP2005/004749)

Examiner : Not Yet Assigned

I.A. Filed : March 17, 2005

Confirmation No. : 1323

For : SOLDER COMPOSITION AND METHOD OF BUMP FORMATION
THEREWITH

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop AMENDMENT
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

In accordance with the duty of disclosure under 37 C.F.R. §§1.56 and 1.97-1.98, Applicant hereby brings the following information to the attention of the Examiner, which includes information cited and discussed in the specification and the International Search Report, issued in connection with counterpart International Patent Application No. PCT/JP2005/004749. A copy of the International Search Report (in English and Japanese), was enclosed with the papers when entering the National Stage on August 18, 2006. The Examiner is invited to review these materials to inspect the relevance indicated during international examination with respect to the documents cited therein.

- (1) Japanese Laid-Open Patent Application Publication No. HEI 6-125169 A,
together with an English language Abstract of the same;
- (2) Japanese Laid-Open Patent Application Publication No. HEI 11-346050 A,
together with an English language Abstract of the same;
- (3) Japanese Laid-Open Patent Application Publication No. HEI 05-000391 A,
together with an English language Abstract of the same;
- (4) Japanese Laid-Open Patent Application Publication No. HEI 06-182579 A,
together with an English language Abstract of the same;
- (5) Japanese Laid-Open Patent Application Publication No. HEI 05-096396 A,
together with an English language Abstract of the same; and
- (6) Japanese Laid-Open Patent Application Publication No. HEI 11-077376 A,
together with an English language Abstract of the same.
- (7) Japanese Laid-Open Patent Application Publication No. 2000-094179 A,
together with an English language Abstract of the same. Applicants note
that this document is cited beginning at page 1 of the specification of the
above-captioned application;
- (8) Japanese Laid-Open Patent Application Publication No. 2001-068848 A,
together with an English language Abstract of the same;
- (9) Japanese Laid-Open Patent Application Publication No. 2001-284793 A,
together with an English language Abstract of the same;
- (10) Japanese Laid-Open Patent Application Publication No. HEI 1-157796 A,
together with an English language Abstract of the same; and

(11) U.S Patent Application No. 10/598,142 to SHIRAI et al., which was filed on August 18, 2006.

Applicants note that above-note documents (1) – (6) were cited in the International Search Report.

Further to the U.S. Patent and Trademark Office's decision to waive the requirement under 37 C.F.R. §1.98 (a)(2)(iii) if the U.S. patent application was filed after June 30, 2003, a copy of the U.S. patent application is not enclosed herewith. However, if a copy is needed, the Examiner is respectfully requested to contact the undersigned.

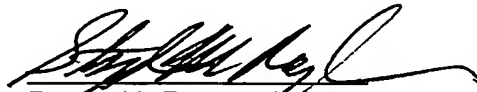
Also, when the above-noted pending application is published, the Examiner is respectfully requested to list its publication number on a PTO 1449 Form (or PTO 892 Form) to confirm consideration thereof.

Applicants respectfully request that the Examiner consider the above material and cite the same. Copies of the above-noted foreign documents, including the noted English language Abstracts, are attached hereto, and all of the documents are listed on an attached PTO-1449 Form. The Examiner is requested to initial the appropriate spaces on the attached Form and to return a copy of the completed Form to Applicants with the next official communication in the present application.

Applicants note that an Office Action on the merits has not issued in the present application, and thus, no fee is believed necessary to ensure consideration of the submitted material.

Should the Examiner have any questions, the Examiner is invited to contact the undersigned at the below-listed telephone number.

Respectfully submitted,
Isao SAKAMOTO et al.

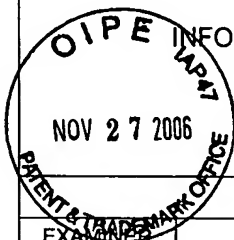


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FORM PTO-1449

U.S. Department of Commerce
Patent and Trademark OfficeAtty. Docket No.
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10/598,124INFORMATION DISCLOSURE STATEMENT
BY APPLICANT

(Use several sheets if necessary)

Applicant
Isao SAKAMOTO et al.Filing Date
August 18, 2006Group
Unknown

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
6	- 1 2 5 1 6 9	05/06/94	JAPAN			
11	- 3 4 6 0 5 0	12/14/99	JAPAN			
5	- 0 0 0 3 9 1	01/08/93	JAPAN			
6	- 1 8 2 5 7 9	07/05/94	JAPAN			
5	- 0 9 6 3 9 6	04/20/93	JAPAN			
11	- 0 7 7 3 7 6	03/23/99	JAPAN			
2000	- 0 9 4 1 7 9	04/04/00	JAPAN			
2001	- 0 6 8 8 4 8	03/16/01	JAPAN			
2001	- 2 8 4 7 9 3	10/12/01	JAPAN			
01	- 1 5 7 7 9 6	06/21/89	JAPAN			

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

1	U.S. Patent Application No. 10/598,142 to SHIRAI et al., which was filed on August 18, 2006.
2	English language Abstract of JP 6-125169.
3	English language Abstract of JP 11-346050.
4	English language Abstract of JP 5-000391.
5	English language Abstract of JP6-182579.
6	English language Abstract of JP 05-096396.
7	English language Abstract of JP 11-077376.
8	English language Abstract of JP 2000-094179.
9	English language Abstract of JP 2001-068848.
10	English language Abstract of JP2001-284793.
11	English language Abstract of JP 1-157796.

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.